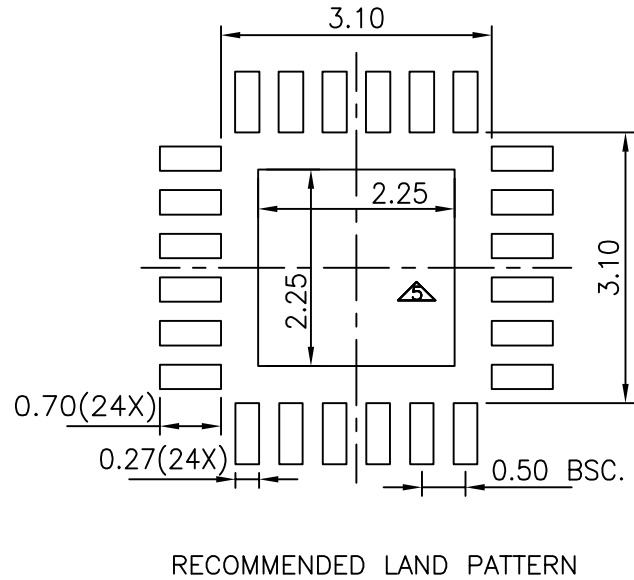
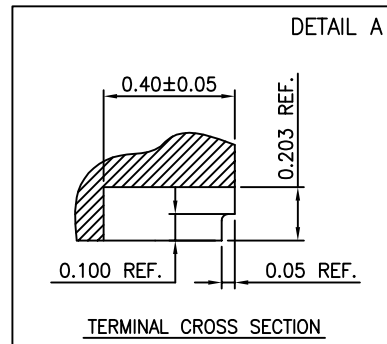


SYMBOLS	MIN.	NOM.	MAX.
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.18	0.25	0.30
D	3.90	4.00	4.10
E	3.90	4.00	4.10
e	0.50 BSC		
D2	2.20	2.25	2.30
E2	2.20	2.25	2.30
L	0.35	0.40	0.45



- NOTE :
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
  2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
  3. REFER JEDEC MO-220
  4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
  5. THERMAL PAD SOLDERING AREA

DATE: 11/23/17

**DIODES** INCORPORATED **PERICOM** A PRODUCT LINE OF DIODES INCORPORATED  
ENABLING SERIAL CONNECTIVITY

**DESCRIPTION: 24-Contact, Very Thin Quad Flat No-Lead (TQFN)**

**PACKAGE CODE: ZDQ (ZDQ24)**

**DOCUMENT CONTROL #: PD-2236** **REVISION: --**